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COOL-BOND
CB8205-EJD

Cure In-situ
Pressure Sensitive
Electrically Conductive
Film Adhesive

IDEAL FOR:

- Component Attach**
- Heat Sink Attach**
- Substrate Attach**

DESCRIPTION:

CB8205-EJD is a silver filled, low bond strength thermoplastic film adhesive. It is designed for bonding heat-sink, component, and substrate. It is electrically and thermally conductive. It is a modified version of CB8205 designed to have improved bond strength at elevated temperature.

CB8205-EJD provides more than 60 psi as applied. When fully cured in-situ during operation, the bond strength reaches over 600 psi at ambient temperature. It also maintains more than 200 psi at 125°C.

AVAILABILITY:

CB8205-EJD is available in sheet sizes or as custom preforms. Standard thicknesses are 0.003" and 0.006". Special thicknesses are available.

APPLICATION PROCEDURES:

- (1) Keep product at room temperature for 15 minutes before using.
- (2) Cut or pre-cut to desired size. Remove one side of release liner from adhesive.
- (3) Place on substrate or component with rolling finger pressure, then remove the other release liner.
- (4) Place component on substrate with insertion pressure of 15 psi or more.

TYPICAL PROPERTIES*

Electrical Resistivity (25°C / 1 minute)	<5x10 ⁻³ ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	-25
Lap-Shear Strength	>200 psi >1.4 N/mm ²
Device Push-off Strength	>600 psi >4.1 N/mm ²
Hardness (Type)	<40
Cured Density (gm/cc)	N/A
Thermal Conductivity	40 Btu-in/hr-ft ² -°F 5.7 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	110
Maximum Continuous Operation Temp. (°C)	150

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

Temperature	Time	Pressure
Burn in Temp	open	N/A

SHELF LIFE:

Storage temperature	Shelf Life
0-5°C	1 yr in sealed package

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer to MSDS for more details.

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